

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 3, line 10, with the following rewritten paragraph:

An aspect of the present invention involves a method of transferring wafers into and out of a thermal treatment chamber in a thermal treatment installation. The treatment chamber has a top section and a bottom section between which the wafer is accommodated during treatment. As illustrated in Figure 12, the thermal treatment installation 100 has a loading chamber 120 in which one wafer 6 of a set of wafers is combined with a ring 1 in a wafer/ring combination. The loading chamber 120 has loading means for placing the wafer 6 on a wafer support 1 and transport means **[[50]]**for moving the wafer/ring combination. The wafer 6 is placed on the wafer support 1 with the loading means while in the loading chamber 120, wherein the wafer support 1 is configured as a ring having support elements to support the wafer 6. The wafer support 1 loaded with the wafer 6 is inserted into the thermal treatment chamber 110 of the reactor 10 using the transport means **[[50]]**so that the wafer 6 and the wafer support 1 are positioned between the top section and the bottom section in the thermal treatment chamber 110. The wafer 6 is individually processed in the thermal treatment chamber 110. After processing the wafer 6, the wafer support 1 is removed from the thermal treatment chamber 110.